

1A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER
FEATURES:

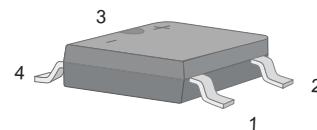
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1 A
- High Surge Current Capability
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg 0.0029oz

PINNING

| PIN | DESCRIPTION |
|-----|----------------------|
| 1 | Input Pin (~) |
| 2 | Input Pin (~) |
| 3 | Output Anode (+) |
| 4 | Output Cathode (-) |



ABS/LBF Package

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

| Parameter | Symbols | TB1S-10 | TB2S-10 | TB4S-10 | TB6S-10 | TB8S-10 | TB10S-10 | Units |
|-------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------|-------------------|---------|---------|---------|---------|----------|-------|
| Maximum Repetitive Peak Reverse Voltage | V _{RRM} | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V _{RMS} | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC Blocking Voltage | V _{DC} | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Average Rectified Output Current at Ta = 40 °C | I _o | 1 | | | | | | A |
| Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method) | I _{FSM} | 35 | | | | | | A |
| Forward Voltage per element @I _F =1.0A | V _F | 1.1 | | | | | | V |
| Maximum DC Reverse Current at Rated DC Blocking Voltage @T _A =25 °C @T _A =100°C @T _A =125 °C | I _R | 5.0 100 500 | | | | | | µA |
| Typical Junction Capacitance (Note1) | C _j | 13 | | | | | | pF |
| Typical Thermal Resistance (Note2) | R _{θJA} R _{θUL} | 80 16 | | | | | | °C/W |
| Operating and Storage Temperature Range | T _j , T _{stg} | -55 ~ +150 | | | | | | °C |

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 1.3mm² copper pad.

Fig.1 Average Rectified Output Current Derating Curve

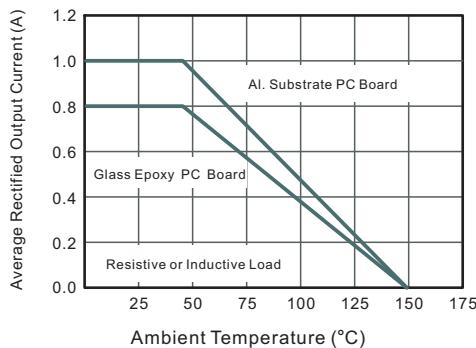


Fig.2 Typical Reverse Characteristics

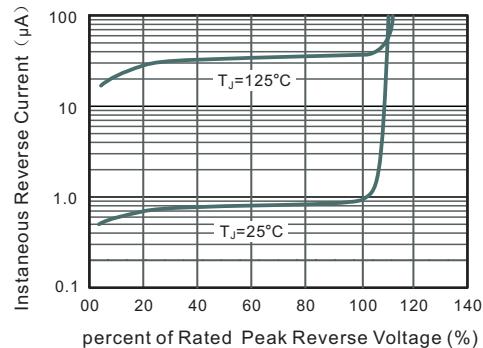


Fig.3 Typical Instantaneous Forward Characteristics

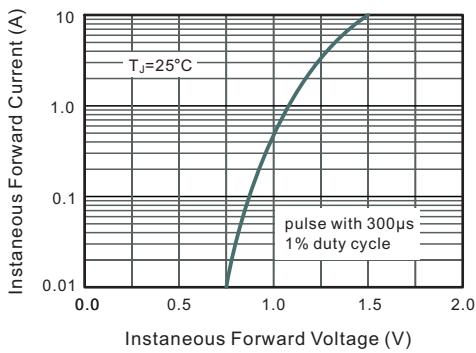


Fig.4 Typical Junction Capacitance

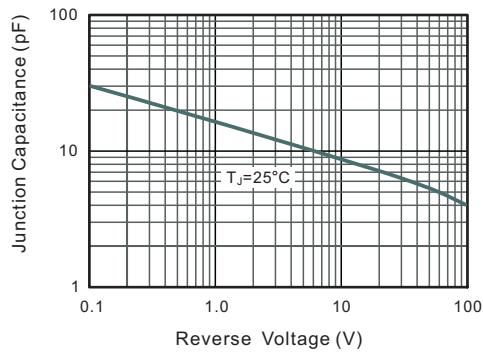
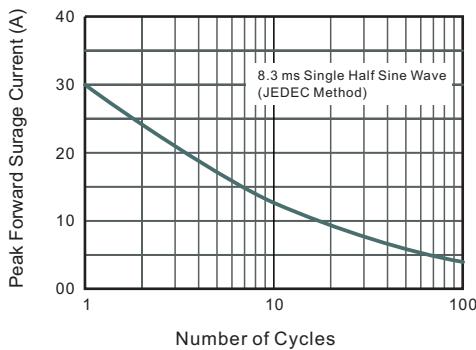


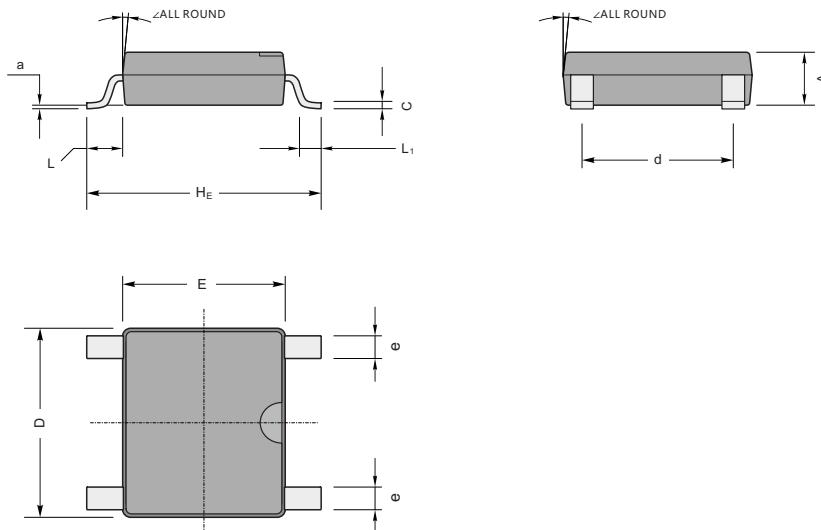
Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

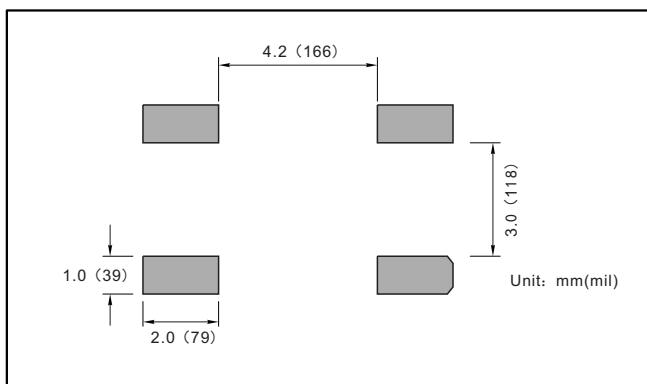
ABS/LBF



ABS/LBF mechanical data

| UNIT | | A | C | D | E | H _E | d | e | L | L ₁ | a | ∠ | |
|------|-----|-----|------|-----|-----|----------------|-----|-----|------|----------------|-----|----|--|
| mm | max | 1.5 | 0.22 | 5.2 | 4.5 | 6.4 | 4.2 | 0.7 | 0.95 | 0.6 | 0.2 | 7° | |
| | min | 1.3 | 0.15 | 4.9 | 4.2 | 6.0 | 3.8 | 0.5 | | | | | |
| mil | max | 59 | 8.7 | 205 | 177 | 252 | 165 | 28 | 37 | 24 | 4 | | |
| | min | 51 | 5.9 | 193 | 166 | 236 | 150 | 20 | | | | | |

The recommended mounting pad size



Marking

| Type number | Marking code |
|-------------|--------------|
| TB1S-10 | 10T1 |
| TB2S-10 | 10T2 |
| TB4S-10 | 10T4 |
| TB6S-10 | 10T6 |
| TB8S-10 | 10T8 |
| TB10S-10 | 10T10 |

